A. Interconnect & Package 분과

2021년 1월 27일(수), 13:00–14:30 / 채널 C

[WC3-A] Emerging Interconnect Ⅰ

좌장: 김병준 교수 (안동대학교), 최두호 교수 (동의대학교)

Session	Presentation
WC3-A-1 13:00-13:30	[초청] **New Materials and Processes for Interconnect Scaling, and Beyond the Scaling Limit** Sang Hoon Ahn, Woojin Lee, Iksoo Kim, Kihyun Hwang *Foundry Process Development Team, Samsung Electronics Co., Ltd.*
WC3-A-2 13:30-14:00	[초청] **Suppression of Volmer-Weber Metallic Growth via Surface Modification of Oxide Substrate for the Applications in Transparent Electrodes and Transparent Heaters** Dooho Choi *Advanced Materials Engineering, Dong-Eui University*
WC3-A-3 14:00-14:15	**DC Magnetron Sputter 방식으로 증착한 비정질 탄소막의 내에칭 특성연구** Sungtae Kim, Cheol Kim, Seung-Hyun Oh, and Young-Chang Joo *Department of Materials Science Engineering, Seoul National University*
WC3-A-4 14:15-14:30	**Co-sputtered CoAl Thin Films as an Alternative Material for VLSI Interconnects** Kyeong-Youn Song[1] and Hoo-Jeong Lee[1,2] *[1]SKKU Advanced Institute of Nano Technology (SAINT), Sungkyunkwan University,* *[2]School of Advanced Materials Science and Engineering, Sungkyunkwan University*

1월 27일 (수)